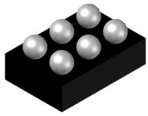
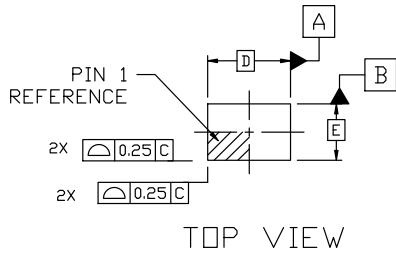


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

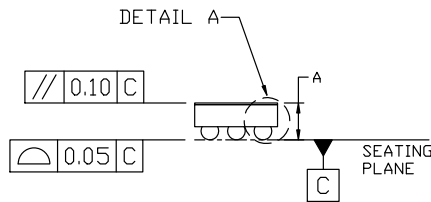


**WLCSP6 1.25x0.85x0.559**  
CASE 567GZ  
ISSUE C

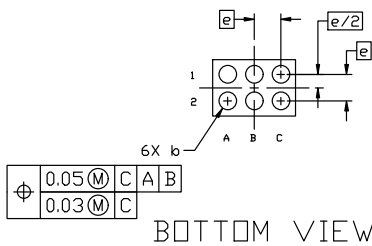
DATE 16 JUN 2022



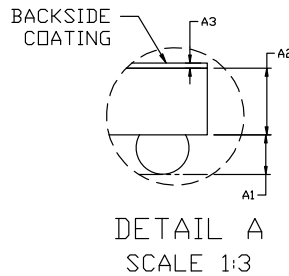
TOP VIEW



SIDE VIEW



BOTTOM VIEW

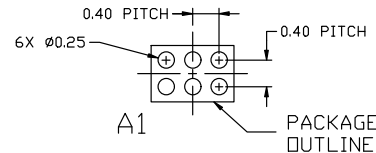


DETAIL A  
SCALE 1:3

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

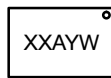
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.509	0.559	0.609
A1	0.174	0.199	0.224
A2	0.310	0.335	0.360
A3	0.025 BSC		
b	0.240	0.265	0.290
D	1.25 BSC		
E	0.85 BSC		
e	0.40 BSC		



RECOMMENDED  
MOUNTING FOOTPRINT\*

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC  
MARKING DIAGRAM\*



A = Assembly Location  
Y = Year  
W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>WLCSP6 1.25x0.85x0.559</b>	<b>PAGE 1 OF 1</b>

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